

Stiftheisten RM 1,27mm, gerade/gewinkelt, 1-/2-reihig - Rundstifte 0,42mm Pin Headers, 1.27mm Pitch, Straight/Right-Angled, Single/Double Row - 0.42mm Round Pins

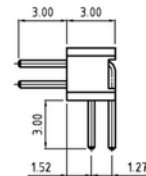
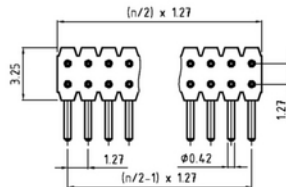
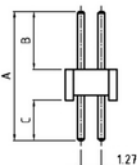
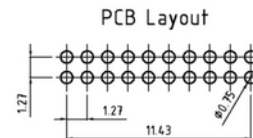
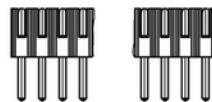
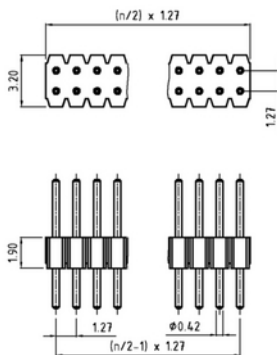
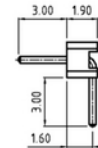
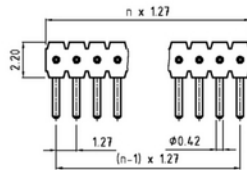
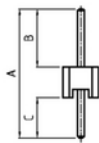
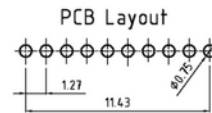
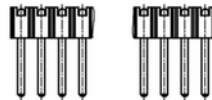
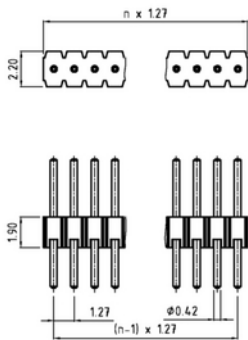
Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplastischer Kunststoff, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Rundstift Ø0,42mm, Kupferlegierung <i>Ø0,42mm round pin, copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm) <i>Acc. to options (see below), over Ni (1.3 ... 2.5µm)</i>
Lötbarkeit <i>Solderability</i>	IEC 60512-12A <i>IEC 60512-12A</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20mΩ <i>< 20mΩ</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 1000MΩ <i>> 1000MΩ</i>
Spannungsfestigkeit <i>Test Voltage</i>	500V _{AC} <i>500V_{AC}</i>
Nennstrom <i>Current Rating</i>	1A <i>1A</i>
Temperaturbereich <i>Temperature Range</i>	-55°C ... +125°C <i>-55°C ... +125°C</i>
Verarbeitung <i>Processing</i>	Wellen- oder Reflow-Lötverfahren <i>Wave or reflow soldering</i>



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Passende Buchsenleisten:
Mate with Female Headers:
155 etc.
Weitere siehe Kapitel B
Please see ch. B for more



Series	Dimensions*	Type*	Contacts*	Plating*
755	07	10	001	00

07 A=8,00 B=3,60 C=2,50mm
09 A=8,60 B=4,20 C=2,50mm
13 A=12,90 B=8,50 C=2,50mm
16 A=17,90 B=13,50 C=2,50mm
17 A=20,30 B=15,90 C=2,50mm
91 Einreihig, gewinkelt (s. Zng.)
Single row, right-angled (as shown in dwg.)
92 Zweireihig, gewinkelt (s. Zng.)
Double row, right-angled (as shown in dwg.)
99 Kundenspezifisch
Customer-specific

10 Einreihig, gerade
Single row, straight
11 Einreihig, gewinkelt (nur Dim. Code 91)
Single row, right-angled (dim. code 91 only)
20 Zweireihig, gerade
Double row, straight
21 Zweireihig, gewinkelt (nur Dim.Code 92)
Double row, right-angled (dim. code 92 only)

001-050 Einreihig
Single row
002-100 Zweireihig
Double row
00 Vergoldet
Gold plated
50 Verzinkt
Tin plated

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
 * This is an **order example** - please replace by your specifications.

Informationen zum Wellen-Lötverfahren Wave Soldering Information

Empfehlungen für das Wellenlötverfahren Recommendations for Wave Soldering

Die Bauteile sollten bei einer Lötbadtemperatur von 260°C in max. 5 Sekunden verlötet werden.
Items should be soldered at a solder temperature of 260°C in 5 seconds max.

Empfohlenes Wellenlötprofil:
Recommended wave soldering profile:



Informationen zum Reflow-Lötverfahren Reflow Soldering Information

Reflow-Löttempfehlung Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150°C
Temperatur Maximum T_{Smax}	200°C
Dauer $T_{Smin} - T_{Smax}$	60-180s
Temperatur Lötbereich T_L	217°C
Verweildauer oberhalb T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Höchsttemperatur T_P	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Dauer 25°C - Höchsttemperatur T_P	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150°C
Maximum Temperatur T_{Smax}	200°C
Duration $T_{Smin} - T_{Smax}$	60-180s
Soldering Range Temperature T_L	217°C
Duration above T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Peak Temperature T_P	260°C ±5
Duration Peak Temperature	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Duration 25°C - Peak Temp. T_P	Max. 8min

